

Accurate and Efficient Gate-Level Parametric Yield Estimation Considering Correlated Variations in Leakage Power and Performance

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Abstract

Increasing levels of process variation in current technologies have a major impact on power and performance, and result in parametric yield loss. In this work we develop an efficient gate-level approach to accurately estimate the parametric yield defined by leakage power and delay constraints, by finding the joint probability distribution function (jpdf) for delay and leakage power. We consider inter-die variations as well as intra-die variations with correlated and random components. The correlation between power and performance arise due to their dependence on common process parameters and is shown to have a significant impact on yield in high-frequency bins. We also propose a method to estimate parametric yield given the power/delay jpdf that is much faster than numerical integration with good accuracy. The proposed approach is implemented and compared with Monte Carlo simulations and shows high accuracy, with the yield estimates achieving an average error of 2%.

Categories and Subject Descriptors: Performance Analysis and Design Aids

General Terms: Reliability, Performance

Keywords: Yield, Variability, Leakage, Correlation

1. Introduction and Overview of Approach

Process variability has grown in recent technologies due to random dopant effects in small devices, the patterning of features smaller than the wavelength of the optical lithography system and related trends. These variations have a tremendous impact on both power and performance of current integrated circuit (IC) designs. In particular, leakage power has grown to contribute a significant fraction of total power and is known to be highly susceptible to process variations due to its exponential dependence on threshold voltage [1]. In [2], a 20X variation in leakage power for 30% delay variation between fast and slow dies is reported. Due to the inverse correlation of power and delay, most of the fastest chips in a lot are found to have unacceptable leakage and vice versa. This leads to a two-sided constraint on the feasible region in the parametric space and results in significant parametric yield loss.

This yield loss will worsen in future technologies due to increasing process variations and the continued significance of leakage power. Another troublesome observation is that increased variation not only results in a larger spread of leakage power but also in higher average leakage power. Most current optimization approaches do not consider process variations and are unaware of their impact on yield. These approaches invariably result in the formation of a timing wall and result in yield loss due to increased susceptibility to process variations [3].

Several approaches were recently proposed to perform statistical timing or power optimization [4-6], however these approaches neglect the correlation of power and performance, and therefore performing timing yield optimization results in yield loss due to

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DAC 2005, June 13–17, 2005, Anaheim, California, USA.

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the power constraint while power minimization techniques will harm timing-based yield. Hence, there is a critical need to develop accurate and computationally efficient yield estimation approaches in order to enable yield-driven optimization tools.

Previous work in yield estimation has been limited to predicting either timing [7-12] or (leakage) power yield [13]. Recently [14] presented a chip-level approach to estimate the yield in separate frequency bins given a power constraint. This high-level approach is based on global circuit parameters such as the total device width on a chip. Since it does not use circuit specific information from a gate-level netlist, it is difficult to use for optimization of gate-level parameters, such as the threshold voltage and sizes of individual gates. Another important requirement for an accurate yield estimation approach is to consider all classes of variations which have significantly different impact on delay [15] and power [13]. Process variations are typically classified into inter-die and intra-die components. Intra-die variations are further classified as having correlated and random components. Traditionally inter-die variations have been the dominant source of variations but with process scaling, the random and correlated components of intra-die variations now exceed inter-die variations [16]. The relative magnitude of these components of variation also depends on the process parameter being considered. For example, gate-length variations are generally considered to have roughly comparable random and correlated components whereas gate-length independent threshold voltage is commonly assumed to vary randomly due to random dopant fluctuations [17].

In this work we propose a novel approach to compute the parametric yield of a circuit with high efficiency and accuracy given leakage power and delay constraints. To the best of our knowledge, this is the first such gate-level approach to estimating parametric yield. The variations in process parameters are assumed to be normally distributed. We model the correlated components using a principal component based approach that allows us to express the underlying variations in terms of independent Gaussian random variables (RVs) and consider both inter-die variations and the correlated component of intra-die variations. We perform statistical timing analysis in the spirit of [7] with an additional random component of variation that is not explicitly considered in [7]. Since it is impractical to maintain a separate RV for the random component associated with each gate in a circuit, we lump all random variations into one additional term.

We then develop an approach to perform statistical leakage power analysis and express the circuit leakage power in terms of the same underlying process variations used to express the delay of the circuit. With increasing circuit size the impact of the random component of variation on the variance of power reduces to zero due to the central limit theorem [18]. Thus, although the random component impacts the statistical circuit delay, the correlation between the random components of power and delay has a vanishingly small impact on the overall correlation in power and delay. Our results show that even for small circuits with a few hundred gates, the random component has negligible impact on the overall variance of power. This allows us to calculate the correlation in power and delay, and to construct their joint probability distribution function (jpdf).

Table 1. Estimated yield for different values of correlation coefficients. Power constraint is set at 1.5X nominal power.

	Estimated Yield		
	Corr = -1.0	Corr = 0.0	Corr = 1.0
Yield	max	$(0.5+\Phi(D))^*$	0.5+
Expression	$(\Phi(D)+\Phi(P),0)$	$(0.5+\Phi(P))$	$\Phi(\min(D,P))$
D=-1	0.000	0.095	0.159
D=0	0.100	0.300	0.500
D=1	0.441	0.505	0.600
D=2	0.577	0.586	0.600
D=3	0.599	0.599	0.600

Based on this jpdf of delay and power we develop a closed-form approach to estimate the yield of a design given the delay and leakage constraints. To demonstrate the importance of the power/delay correlation, Table 1 shows yield for varying values of correlation factors at which simple expressions for yield can be obtained. $\Phi(x)$ represents the value of the Gaussian cumulative distribution function at x . The yields are estimated for delay constraints of ‘ D ’ standard deviations (SD) from the mean at a fixed power constraint ‘ P ’. The results in Table 1 clearly show that the correlation of power and delay has a strong impact on parametric yield, particularly for mid- to high-performance speed bins.

The remainder of the paper is organized as follows. Section 2 briefly reviews the principal component based approach to model process variations. Section 3 presents the core statistical power and timing analysis approaches. In Section 4 we develop an approach to estimate the yield given power and delay constraints. Section 5 presents the results and compares our approach to Monte Carlo circuit simulations. We conclude in Section 6.

2. Modeling Process Variations

This section details the variability modeling infrastructure used in our work. Much of this framework is similar in spirit to [7,9] for statistical timing analysis – we also use the same models to consider leakage variability such that the correlation between power and delay is preserved for yield estimation.

In this paper we consider process variations in gate length and gate length-independent threshold voltage (V_{th0}) although the approach can be easily extended to consider other sources of variations. The process parameters are expressed as a sum of correlated and random components and the sum of variances of both these components provide the overall variation in the process parameter. To handle the correlated components of variations (inter-die and correlated intra-die) the overall chip area is divided into a grid as shown in Figure 1. In the absence of inter-die process variations the correlation coefficient varies from one (within the same square of the grid) and falls off to zero with increasing distance. Due to inter-die process variations squares on the grid that lie at the opposite corners are correlated and the correlation will fall off to a value higher than zero that depends on the relative contribution of inter-die variations to the correlated variation. Each square in the grid corresponds to a RV of the process parameter which has correlations with all other RVs corresponding to other squares in the grid. The values at the bottom right corner of each of the grids show the correlation coefficients with the top-left square on the grid. Squares that are much further apart clearly demonstrate lower correlation compared to that of adjacent squares on the grid in this model.

To simplify the problem, this set of correlated RVs is replaced by another set of mutually independent RVs with zero mean and unit variance using the principal components of the set of correlated RVs. A vector of RVs (say X) with a correlation matrix C , can be expressed as a linear combination of the principal components Y as:

$$X = \Delta_x + \Omega V^{-1} D^{1/2} Y \quad (1)$$

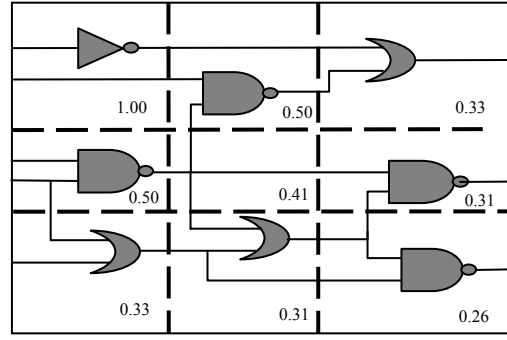


Figure 1. Example partitions of a circuit using a grid to model the correlated component of variations (correlation coefficients referenced to top-left element).

where Δ_x is the vector of the mean values of X , Ω is a diagonal matrix with the diagonal elements being the standard deviations of X , V is the matrix of the eigenvectors of C , and D is a diagonal matrix of the eigenvalues of C . Since the correlation matrix of a multivariate (nondegenerate) Gaussian RV is positive-definite, all elements of D are positive and the square-root in (1) can be evaluated. We express the delay and leakage power¹ of an individual gate as shown in (2):

$$\begin{aligned} Delay &= d_{nom} + \sum_{i=1}^p \alpha_p (\Delta P_p) \\ Leakage &= \exp \left(V_{nom} + \sum_{i=1}^p \beta_p (\Delta P_p) \right) \end{aligned} \quad (2)$$

where d_{nom} and $\exp(V_{nom})$ are the nominal values of delay and leakage power respectively, and the α 's and β 's represent the sensitivities of delay and the log of leakage to the process parameters under consideration. The variable ΔP_p represents the change in the process parameters from their nominal value.

In a statistical scenario, the process parameters are modeled as RVs. If the overall circuit is partitioned using a grid as shown in Figure 1, the delay of individual gates can be expressed as a function of these RVs. Using the principal component approach, the delay in (2) can then be expressed as:

$$Delay = d_{nom} + \sum_{i=1}^p \left(\alpha_p \sum_{j=1}^n \gamma_{ji} z_j \right) + \eta_d R \quad (3a)$$

where z_j 's are the principal components of the correlated RV's ΔP_p 's in (2) and the γ 's can be obtained from (1). $R \sim N(0,1)$ in the above equation represents the random component of the variations of all process parameters lumped into a single term that contributes a total variance of η_d^2 to the overall variance of delay. Similarly the leakage power for an individual gate can be expressed as:

$$Leakage = \exp \left(V_{nom} + \sum_{i=1}^p \left(\beta_p \sum_{j=1}^n \gamma_{ji} z_j \right) + \eta_l R \right) \quad (3b)$$

The next section shows that these representations of delay and power allow for significant simplification in the joint timing and power analysis, which otherwise becomes computationally inefficient if the spatial correlation is maintained without such a unified principal component approach.

3. Statistical Analysis

In this section we first provide an overview of the statistical timing analysis in [7] which we have extended to consider both

¹ Since variations in dynamic power are typically much smaller than those observed in static power, we focus on statistical leakage power analysis for yield estimation in this paper.

correlated and random components of variations. We then provide the details of the approach for performing statistical leakage power analysis. During timing analysis the arrival time at each node is maintained in the same canonical form as the delay of the individual gates, which enables an efficient approach for the traversal of the timing graph. Similarly, during power analysis the sum of leakage power is maintained in a canonical form as the leakage of different gates is summed.

3.1 Timing Analysis

The delay of each gate (say a) can be expressed as follows using the expression developed in the previous section:

$$D_a = a_0 + \sum_{i=1}^n a_i z_i + a_{n+1} R \quad (4)$$

This serves as the canonical expression for delay. The mean delay is simply the nominal delay (a_0). Since the principal components (z_i 's) are uncorrelated $N(0,1)$ RVs, the variance of the delay can be expressed as:

$$Var(D_a) = \sum_{i=1}^n (a_i^2) + a_{n+1}^2 \quad (5)$$

and the covariance of the delay with one of the principal components can be obtained as:

$$Cov(D_a, z_i) = E(D_a z_i) - E(D_a)E(z_i) = a_i^2 \quad \forall i \in \{1, 2, \dots, n\} \quad (6)$$

In [9], it was shown that delay distributions arising due to correlated reconvergent fanouts can be tightly upper-bounded by assuming them to be independent. Since the random components are uncorrelated and do not contribute to the covariance of the delay at the two nodes at the input of a gate (e.g., 'a' and 'b'), the covariance can be obtained as:

$$Cov(D_a, D_b) = \sum_{i=1}^n a_i b_i \quad (7)$$

In deterministic timing analysis the delay of the circuit is found by applying two functions to the delay of individual gates: sum and max. Similar functions for the canonical delay expressions (4) are defined as:

$$Sum(D_a, D_b) = (a_0 + b_0) + \sum_{i=1}^n (a_i + b_i) z_i + \sqrt{a_{n+1}^2 + b_{n+1}^2} R \quad (8)$$

The max function of normally distributed RVs is not a strict Gaussian. References [7,19] have shown that the maximum of two Gaussian RVs can be closely approximated by another Gaussian. If

$$c = \max(a, b) \quad (9)$$

where a and b are Gaussian RV's, then the parameters of c , which is assumed to be Gaussian, can be obtained using expressions developed in [20]. This approach provides the mean and variance of c in terms of the mean and variance of a and b and their correlation coefficient. Reference [20] also develops expressions to evaluate the correlation of c with any other RV in terms of the correlation of the RV with a and b . In the spirit of [7,8] we assume that c can again be expressed in the same canonical form as a and b . To find the coefficients in the expression for c in canonical form, the mean, variance and the correlations of c with the principal components are matched, giving

$$\begin{aligned} c_0 &= E(\max(a, b)) \\ c_i &= \text{cov}(c, z_i) = \text{cov}(\max(a, b), z_i) \quad \forall i \in \{1, \dots, n\} \\ c_{n+1} &= \left(\text{Var}(\max(a, b)) - \sum_{i=1}^n c_i^2 \right)^{1/2} \end{aligned} \quad (10)$$

By modeling the random component, we can preserve the mean, variance, and correlations, avoiding the need to scale the

coefficients of the principal components to match variance, which loses their correlation [7]. To compute the max of more than two variables the above technique is applied recursively.

Using the timing analysis approach outlined above, we can develop an expression for the delay of a circuit in terms of the RVs associated with process parameter variations. In the next sub-section we develop an approach for gate-level statistical leakage power analysis. The key in this step is to preserve the correlation in delay and power, which is achieved by using a similar principal component based approach with the same underlying RVs.

3.2 Power Analysis

We express the leakage power of each gate as a lognormal (exponential of a Gaussian) RV based on the power model discussed in Section 2. The leakage power of the total circuit can then be expressed as a sum of correlated RVs. This sum can be accurately approximated as another lognormal random variable [21]. Reference [21] shows that the approximation performed using an extension of Wilkinson's method [22] (based on matching the first two moments) provides good accuracy. The leakage power of an individual gate a is expressed as

$$P_{leak}^a = \exp\left(a_0 + \sum_{i=1}^n a_i z_i + a_{n+1} R\right) \quad (11)$$

where the z 's are principal components of the RVs and the a 's are the coefficients obtained using (1) and (2). The mean and variance of the RV in (11) can then be computed as

$$E(P_{leak}^a) = \exp\left(a_0 + \frac{1}{2} \sum_{i=1}^{n+1} a_i^2\right) \quad (12)$$

$$Var(P_{leak}^a) = \exp\left(2a_0 + \sum_{i=1}^{n+1} a_i^2\right) - \exp\left(2a_0 + \frac{1}{2} \sum_{i=1}^{n+1} a_i^2\right) \quad (13)$$

The correlation of the leakage of gate a with the lognormal RV associated with z_j is found by evaluating

$$E(P_{leak}^a e^{z_j}) = \exp\left(a_0 + \frac{1}{2} \sum_{i=1, i \neq j}^{n+1} a_i^2 + (a_j + 1)^2\right) \quad \forall j \in \{1, 2, \dots, n\} \quad (14)$$

Similarly the covariance of the leakage of two gates (a and b) can be obtained by using

$$E(P_{leak}^a P_{leak}^b) = \exp\left((a_0 + b_0) + \frac{1}{2} \left(\sum_{i=1}^n (a_i + b_i)^2 + a_{n+1}^2 + b_{n+1}^2 \right)\right) \quad (15)$$

We assume that the sum of leakage power can be expressed in the same canonical form as (11). If the random variables associated with all the gates in the circuit are summed in a single step the overall complexity of the approach is $O(n^2)$ due to the size of the correlation matrix. Since the sum of two lognormal RVs is assumed to have a lognormal distribution in the same canonical form, we can use a recursive technique to estimate the sum of more than two lognormal RVs.

In each recursive step we sum two RVs of the form in (11) to obtain another RV in the same canonical form. To find the coefficients in the expression for the sum of the RVs we match the first two moments (as in Wilkinson's method) and the correlations with the lognormal RVs associated with each of the Gaussian principal components. We outline the steps in one of the recursive steps where we sum P_{leak}^b and P_{leak}^c to obtain P_{leak}^a .

$$\begin{aligned} P_{leak}^a &= \exp\left(a_0 + \sum_{i=1}^n a_i z_i + a_{n+1} R\right) \\ &= \exp\left(b_0 + \sum_{i=1}^n b_i z_i + b_{n+1} R\right) + \exp\left(c_0 + \sum_{i=1}^n c_i z_i + c_{n+1} R\right) = P_{leak}^b + P_{leak}^c \end{aligned} \quad (16)$$

The coefficients associated with the principal components can be found using (12-15) and expressing the coefficients associated

with the principal components as

$$a_i = \log \left(\frac{E(P_{leak}^a e^{z_i})}{E(P_{leak}^a)E(e^{z_i})} \right) = \log \left(\frac{E(P_{leak}^b e^{z_i}) + E(P_{leak}^c e^{z_i})}{(E(P_{leak}^b) + E(P_{leak}^c))E(e^{z_i})} \right) \quad (17)$$

Using the expressions developed in [13], the remaining two coefficients in the expression for P_{leak}^a can be expressed as

$$a_0 = \frac{1}{2} \log \left(\frac{(E(P_{leak}^b) + E(P_{leak}^c))^4}{(E(P_{leak}^b) + E(P_{leak}^c))^2 + Var(P_b) + Var(P_c) + 2Cov(P_b, P_c)} \right) \quad (18)$$

$$a_{n+1} = \left[\log \left(1 + \frac{Var(P_b) + Var(P_c) + 2Cov(P_b, P_c)}{(E(P_{leak}^b) + E(P_{leak}^c))^2} \right) - \sum_{i=1}^n a_i^2 \right]^{0.5} \quad (19)$$

Having obtained the sum of two lognormals in the original canonical form, the process can be recursively repeated to compute the expression for the total leakage power of the circuit.

The timing and power analysis techniques outlined in this section can be used to efficiently estimate the individual probability distribution functions of delay and power. The correlation in delay and leakage power arising from the correlated components of variation can be easily estimated since the correlated variations are expressed in terms of the principal components used to develop the expressions for both delay and power.

As will be shown in the results section, the dependence of the variance of leakage power on the random component is very weak. This arises due to the fact that the random component associated with each gate is independent and hence the ratio of standard deviation to mean for the sum of these independent RVs is inversely proportional to the square root of the number of RVs summed [18]. This ratio does not reduce for correlated RVs – therefore if a large number of RVs are summed with both correlated and random components, the overall variance is dominated by the variance of the correlated component. Hence, the correlation due to the random component, which is difficult to compute efficiently, is also insignificant and can be safely neglected.

4. Yield Estimation

The parametric yield of a circuit given delay and power constraints can be expressed as

$$Y = P(D \leq D_0, P \leq P_0) \quad (20)$$

which is the probability of the circuit delay and power being less than D_0 and P_0 respectively. Since delay and power are correlated, the yield cannot be simply computed by multiplying the separate probabilities. To express the yield as the probability of a bivariate Gaussian RV we take the logarithm of the leakage power constraint. The correlation coefficient of the two Gaussian RVs in the yield equation can now be obtained using (7). We express the yield in terms of two $N(0,1)$ RVs N_0 and N_1 as

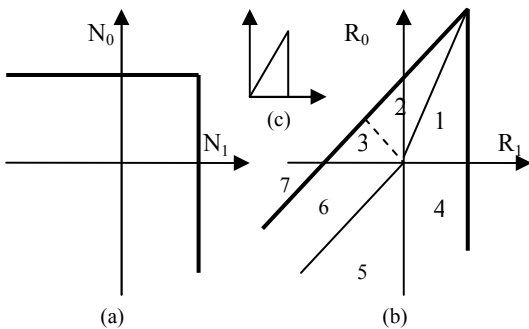


Figure 2. Transformation of the feasible region from (a) to (b) under the transformation expressed in (22) for negative values of correlation.

$$Y = P \left(N_0 \leq \frac{D_0 - \mu_D}{\sigma_D}, N_1 \leq \frac{\log(P_0) - \mu_{\log(P)}}{\sigma_{\log(P)}} \right) \quad (21)$$

Since the correlation coefficient of two RVs does not change under a linear transformation with positive coefficients of the original RVs, the correlation between N_0 and N_1 remains same. One approach to evaluate this expression is to perform numerical integration of the jpdf over the feasible region, but this makes the approach computationally inefficient. A look-up table based approach, though efficient, involves substantial inaccuracy due to the required interpolation as noted in [23]. Hence, we adopt an analytical approach to estimate the yield which makes the approach efficient and practical within a yield optimization framework.

The feasible region defined using two correlated RVs is transformed to a set of two uncorrelated RVs using the following transformation:

$$R_0 = N_0; R_1 = \left(\frac{N_1 - \rho N_0}{(1 - \rho^2)^{1/2}} \right) \quad (22)$$

This transformation maps the feasible region from a rectangle to a triangle as shown in Figure 2 for the case where $\rho < 0$, which is the case of interest. The desired probability can be obtained by using approximate expressions developed in [23] for evaluating probabilities of uncorrelated bivariate Gaussian RVs in regions of the form shown in Figure 2(c). To evaluate the probability of the region shown in Figure 2(b) we partition the figure as shown. The desired probability can then be expressed as a sum of the probabilities in Regions 1-6 which can be evaluated as follows:-

Region 1:

Already in the form required in [23],

Region 2:

Since the integral of the region is circularly symmetric, if the axes are rotated such that the dotted line as shown in Figure 2(b) lies along the x-axis then Region 2 is again in the same form as Figure 2(c),

Region 4:

The probability in this region is

$$P(R_0 \leq 0, 0 \leq R_1 \leq X) \quad (23)$$

where X is the point where the vertical line cuts the R_0 axis. Since R_0 and R_1 are statistically independent, this probability can be simply expressed as

$$P(R_0 \leq 0)P(0 \leq R_1 \leq X) = 0.5\phi(X) \quad (24)$$

where Φ is the normal integral from 0 to x ,

Regions 3, 5 and 6:

The probability for these regions can be expressed as

$$P(R_0 \leq 0, R_1 \leq 0) + P(3+6) - P(6+7) \quad (25)$$

The first and second terms in (25) correspond to a region that has the same form as Region 4 and the region for the third term has the same form as Region 1. Thus, the desired yield expressed in (20) can be efficiently estimated using closed-form expressions.

In terms of computational complexity, the proposed approach differs from [7] in the computation of an extra term associated with the random component. Thus the overall complexity of the timing analysis remains $O(nN_g)$, where n is the number of terms in the delay expression that corresponds to the number of partitions into which the circuit is divided, and N_g is the number of gates in the circuit. The power analysis is similar and requires an additional $O(nN_g)$ steps. The correlation computation requires an additional $O(n)$ steps, and the yield estimation runs in constant time. The computation of the principal components

Table 2. Comparison of our proposed approach and Monte Carlo based simulation results

Benchmark Circuit	Number of gates	Analytical					Error compared to Monte Carlo simulations					Logic Depth	random contribution to delay	random contribution to leakage	Runtime (sec)
		Mean Delay (ns)	SD of delay (ns)	Mean Leakage (μ W)	SD of Leakage (μ W)	Correlation	Mean Delay	SD of delay	Mean Leakage	SD of Leakage	Correlation				
c432	256	0.91	0.04	12.20	4.05	-0.91	0.5%	8.4%	0.1%	11.1%	2.0%	24	5.2%	2.3%	0.02
c499	544	0.89	0.03	36.14	10.29	-0.95	0.4%	11.4%	0.9%	8.8%	4.9%	24	2.7%	1.2%	0.12
c880	500	0.82	0.04	30.00	8.64	-0.88	1.1%	11.1%	1.1%	8.3%	4.9%	19	8.8%	2.5%	0.12
c1908	603	1.22	0.04	19.03	5.38	-0.95	2.1%	11.9%	1.0%	9.2%	4.0%	33	2.3%	2.5%	0.12
c2670	780	0.91	0.04	7.47	2.34	-0.93	1.7%	9.8%	1.7%	10.3%	0.7%	23	6.3%	1.0%	0.18
c3540	1163	1.43	0.06	57.54	14.70	-0.74	2.0%	10.4%	1.3%	6.4%	0.9%	40	3.3%	0.9%	0.56
c5315	1692	1.23	0.04	88.41	20.95	-0.87	1.4%	12.0%	2.7%	5.2%	4.1%	33	4.3%	0.4%	1.92
c6288	3834	3.32	0.11	116.73	25.38	-0.79	2.6%	13.4%	3.6%	5.3%	3.2%	94	0.5%	0.2%	15.43
c7552	2152	1.12	0.04	85.39	20.27	-0.86	0.6%	16.2%	2.5%	5.4%	8.8%	30	18.2%	0.6%	3.79
i2	192	0.47	0.02	4.53	1.46	-0.91	5.0%	20.1%	0.2%	10.1%	4.9%	10	11.6%	2.0%	0.02
i3	120	0.27	0.01	0.83	0.26	-0.89	1.0%	16.8%	1.0%	3.9%	3.6%	6	20.2%	2.3%	0.02
i4	264	0.38	0.02	11.34	3.73	-0.87	2.6%	20.6%	0.9%	8.1%	1.7%	10	14.0%	3.6%	0.04
i5	423	0.34	0.01	20.63	5.98	-0.88	1.0%	17.8%	0.0%	7.3%	8.7%	8	16.8%	3.4%	0.10
i6	461	0.31	0.01	13.90	4.58	-0.88	1.5%	10.4%	0.4%	9.0%	6.4%	8	5.4%	2.3%	0.08
i7	769	0.34	0.02	22.71	6.69	-0.65	3.1%	14.4%	0.6%	10.5%	3.6%	9	15.8%	2.3%	0.20
i8	1013	0.52	0.02	26.71	7.66	-0.94	1.5%	18.0%	1.4%	7.9%	6.6%	13	6.7%	2.3%	0.33
i9	723	0.53	0.02	24.47	7.91	-0.83	1.8%	13.4%	0.6%	3.0%	0.7%	14	5.6%	2.1%	0.16
i10	2482	1.41	0.05	49.55	12.59	-0.86	2.4%	11.1%	2.3%	7.4%	5.5%	39	3.5%	0.5%	5.00
Average		0.91	0.04	34.86	9.05	-0.87	1.8%	13.7%	1.2%	7.6%	4.2%		8.4%	1.8%	

requires $O(pn^3)$ steps where p is the number of process parameters required. The cubic dependence results from the eigenvector computation required during principal component analysis. Since the principal components need to be calculated only once, it does not impact the overall complexity. Hence, the overall complexity of the approach is $O(nN_p)$.

5. Results

We implemented the proposed approach in C++ and compared our results to Monte Carlo (MC) based simulations. The benchmark circuits were synthesized using an industrial 0.13 μ m technology. We consider channel length and gate length-independent threshold voltage variations for our experiments with 3σ /mean of 20%. All variation in V_{th0} was assumed to be random (due to random dopant effects), whereas half the variation in channel length was considered to be correlated. The gates in the library were characterized for delay and leakage power using SPICE simulations for different values of channel length and V_{th0} , which were fit to expressions of the form in (2) using multiple linear regression. The circuits were placed using Cadence Silicon Ensemble, and partitioned such that each square on the grid had a maximum dimension of 40 μ m x 40 μ m. The correlation coefficient among different squares on the grid was assumed to be inversely proportional to the distance between the centers of their grids. MC simulations were performed by generating and summing samples of correlated and independent Gaussian random variables for the process parameters and performing timing and power analysis.

Table 2 shows results for the ISCAS85 [24] and MCNC [25] benchmark circuits (i1 and c17 are excluded due to their very small sizes). The table compares the means and standard deviations of delay and power obtained using the proposed approach and Monte Carlo based simulations. The table also compares the coefficient of correlation of delay and the log of leakage power which is required for yield estimation as discussed in Section 4. The results show that the estimates obtained using the proposed approach for the values of the mean delay and leakage power are very accurate with an average error of 1.2% and 1.8% respectively. The standard deviations show an average error of 7.6% and 13.7% for power and delay respectively. We note that circuits with a smaller logic depth show larger error in delay compared to circuits with a larger logic depth. This results from the fact that the correlations in the random component are neglected, which can result in an overall smaller variance. The second to last column in Table 2 shows the contribution of the random component of

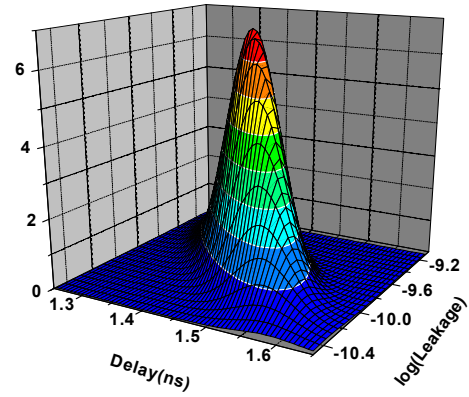


Figure 3. Joint probability distribution function for the bivariate Gaussian distribution for c3540.

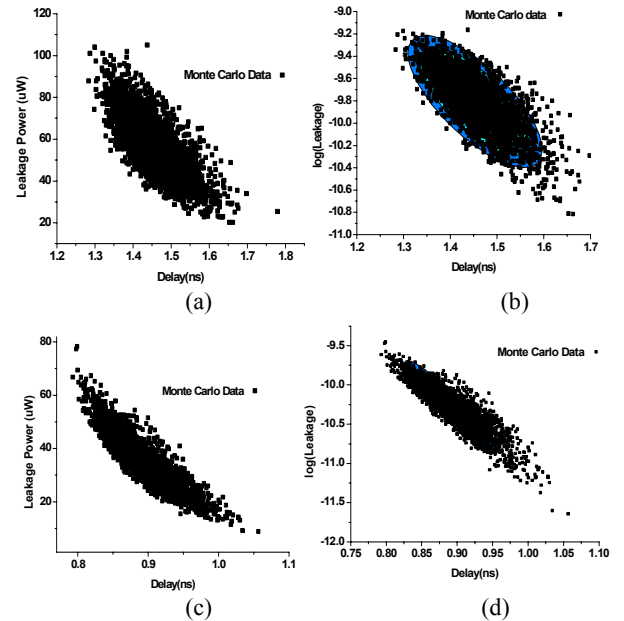


Figure 4. Scatter plots for delay and power obtained using MC simulations. (a-b) c3540 and (c-d) c499. (b,d) are shown over contour plots obtained using our proposed approach. The outer contour corresponds to points 3σ away from the mean.

variation to the variance in delay. Note that circuits which have a larger error have a significant component of the overall variation in delay arising from random variations. The contribution of the random component is inversely proportional to the depth of the critical path [15] and can generally be expected to be small for larger circuits. The coefficient of correlation between the log of leakage power and delay shows a very good match to MC results with an average error of 4.2%. The last column indicates that the overall contribution of the random component to the variance of leakage power is 1.8% on average with a maximum of 3.6%. This confirms our assumption that the impact of the random component of variation is negligible when estimating the correlation in power and performance.

Figure 3 shows a representative jpdf of the log of leakage and delay, which is a bivariate Gaussian jpdf. The contours of the jpdf are ellipses with center at the mean of delay and leakage, which are rotated by an angle depending on the ratio of their variances. As the correlation is allowed to increase to an extreme value of ± 1 , the contours of the jpdf concentrate around the major axis and merge into a line. Figure 4 shows the scatter plots obtained using MC-based simulations for two of the benchmark circuits. The scatter plots on the left show the lognormal nature of leakage power which is more evident for the case of c499 (Figure 4(c)) which is the smaller circuit. Circuit c499 also shows a higher correlation which is evident from the concentration of the jpdf along the major axis of its contours. The scatter plots on the right show the Gaussian nature of the jpdf of the log of leakage and delay, since the shape of the scatter plots closely resembles an ellipse. These plots are laid over the contour plots obtained using our approach and show very good match.

Table 3 compares the yield estimates achieved using the proposed approach of Sections 3 and 4 to those obtained using Monte Carlo based simulations for all benchmark circuits at different performance bins. For both bins the leakage power is constrained to be less than 1.1X the mean leakage value. Two different performance bins are constructed with delay being less than 1.0X and between 1.0 and 1.1X the mean delay. The proposed approach is seen to provide good estimates of the yield for the different frequency bins with an average misprediction in yield of 2%. If the correlation in power and delay is ignored the yield in different bins can be both significantly overestimated (up to 15% in the high-performance bin) and underestimated (up to 16% in the low-performance bin) as shown in the last three columns of the table.

6. Conclusions

To the best of our knowledge, we have presented the first approach to gate-level parametric yield analysis considering correlation between power and performance resulting from various components of variations. The approach is shown to be computationally efficient and can form the basis for yield-driven optimization techniques as opposed to purely timing-yield driven optimizations which dramatically penalize power yield. The proposed approach matches accurately with Monte Carlo based simulations with an average error of 4.2% in estimating power and delay correlation. Yield estimated using this approach is within 2% on average error compared to Monte Carlo, demonstrating that neglecting the correlation in power and performance leads to gross mispredictions in yield.

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Table 3. Yield estimates for different frequency bins using the proposed approach and MC based simulations.

Benchmark Circuit	Monte Carlo		Analytical Yield		Yield Neglecting Correlation	
	$D < D_{\mu}$	$D_{\mu} < D < 1.1 * D_{\mu}$	$D < D_{\mu}$	$D_{\mu} < D < 1.1 * D_{\mu}$	$D < D_{\mu}$	$D_{\mu} < D < 1.1 * D_{\mu}$
c432	0.17	0.43	0.14	0.46	0.31	0.30
c499	0.17	0.46	0.15	0.49	0.32	0.32
c880	0.20	0.43	0.16	0.46	0.32	0.31
c1908	0.18	0.48	0.14	0.49	0.32	0.32
c2670	0.16	0.44	0.14	0.47	0.31	0.30
c3540	0.22	0.43	0.20	0.44	0.33	0.32
c5315	0.19	0.48	0.19	0.48	0.33	0.33
c6288	0.22	0.47	0.21	0.46	0.34	0.34
c7552	0.20	0.47	0.19	0.47	0.33	0.33
i2	0.17	0.40	0.14	0.45	0.31	0.30
i3	0.17	0.40	0.15	0.45	0.31	0.30
i4	0.19	0.40	0.15	0.46	0.31	0.30
i5	0.18	0.45	0.16	0.47	0.32	0.31
i6	0.20	0.39	0.15	0.45	0.31	0.30
i7	0.22	0.38	0.21	0.40	0.32	0.30
i8	0.18	0.46	0.15	0.49	0.32	0.32
i9	0.19	0.44	0.17	0.45	0.31	0.31
i10	0.20	0.46	0.18	0.47	0.33	0.32
Average	0.19	0.44	0.17	0.46	0.32	0.31

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